CUT DOWN YOUR TIME CONSUMING CEMENTING STEPS TO 4 EASY STEPS WITH BIFIX SE

1. Etching
2. Rinse
3. Dry, but do not overdry
4. Apply Primer
5. Scrub Primer
6. Dry Primer
7. Apply Bond
8. Spread bond with air
9. Mix Cement
10. Apply Cement
11. Seat the restoration
12. Remove Excess

TYPICAL TOTAL ETCH RESIN CEMENT

• Time saving – no additional bond, prime or etch steps needed
• Ease of use – gel-phase cleanup, no refrigeration, no hand-mixing or trituration required
• High bond strength without an adhesive
• High flexible strength and low water solubility for long term success

Bifix SE

DUAL-CURED SELF-ADHESIVE UNIVERSAL RESIN CEMENT

TECHNICAL DATA:
- Working time (extra-oral): 90 sec
- Setting time: 4 min
- Film thickness: 5–10 µm
- Curing depth: 2 mm/20 sec
- Water solubility: 1µg /mm 3
- Flexible Strength: 160 MPa (LC), 150 MPa (CC)
- Radiopacity: 227 %Al
- pH (at application): 2.5 (acidic)
- pH (after curing): neutral

• Low 5–10 micron film thickness – cuts down on adjustment time
• Compatibility with common materials – ceramic and zirconia, CAD/CAM materials, PFMs and metal restorations
• Efficient self-cure mode – sets up completely without any light
• Radiopaque for excellent identification under x-ray

Tack light-cure Bifix SE for 1-2 seconds per surface (mesio-oral, disto-oral, mesio-buccal, disto-buccal). The excess gel-like material is easily removed with a scaler.

DUAL-CURED SELF-ADHESIVE UNIVERSAL RESIN CEMENT

Bifix SE

DUAL-CURED SELF-ADHESIVE UNIVERSAL RESIN CEMENT
A new generation of self-adhesive resin cement

Not all self-adhesive resin cements are created equal. Many of the first generation self-adhesive cements had a lack of stability and bond strength which led to some long-term failures. Bifi x SE is a new generation which combines the superior self-bond nano technology of Futurabond DC with the proven cement engineering of Bifi x QM in a new 4:1 mixing ratio. The 4:1 ratio allows the use of a new initiator system to engineer a catalyst that is much more stable than other systems on the market, even without refrigeration. The clinical benefits are higher bond strength, especially on zirconia-based restorations and a lower water solubility, giving Bifi x SE higher long term clinical success rates. Bifi x SE's easy excess removal, fewer working steps and its moisture tolerance, makes it easy to work with.

Versatility

Bifi x SE is versatile to use for cementing crowns, bridges, inlays, onlays and posts. It achieves high bond strength with all common substrates as enamel, dentin, metal, zirconia, composite, ceramic and all CAD/CAM materials.

Speed and Ease Cementing without bonding, primer or etchant

Bifi x SE uses Futurabond DC's superior self-etch adhesive technology and does not need any additional bond, prime or etching steps to achieve high bond strengths on all substrates. This time saving procedure reduces extra working steps which streamlines the workflow of any office. Bifi x SE is dual-cured and allows the clinician to control the setting time. In the light cure mode the material will set quickly (20 secs cures on each side is recommended). In the self-cure mode the user will have 90 secs of working time (extra-orally) and 30-60 secs of working time (intra-orally) with a final set time after insertion of 4 minutes.

Endo-Tips for precise root-canal application

Every Bifi x SE pack includes specially designed endo tips, making the application of the resin cement in the root canal clean and easy.
Bifix® SE

BOND WITH CONFIDENCE

High bond strength to all substances

The key for an excellent resin cement is to achieve high bond strength to all sides of the restoration and to all substances in a light and self-cured mode. Bifix SE, uses polyfunctional adhesive monomers (methacrylic phosphoric acid ester), which allows an even high bond strength to all substrates. This makes Bifix SE a universal cement for multiple indications in light and self-cured modes.

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**BOND TO DENTIN**

- **Bifix SE**: 8.0 MPa (LC), 12.8 MPa (CC)
- **MaxCem Elite**: 5.0 MPa (LC), 6.3 MPa (CC)
- **G-Cem**: 6.8 MPa (LC), 8.8 MPa (CC)
- **RelyX™ Unicem**: 4.5 MPa (LC), 6.0 MPa (CC)
- **RelyX™ Unicem Clicker**: 5.2 MPa (LC), 4.6 MPa (CC)
- **G-Cem®**: 4.6 MPa (LC), 3.9 MPa (CC)


**LC = Light-Curing**

**CC = Chemical-Curing**

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**SHEAR BOND STRENGTH TO IPS EMPRESS CAD BLOCKS**

- **Bifix SE**: 25.0 MPa
- **RelyX™ Unicem Aplicap**: 17.8 MPa
- **RelyX™ Unicem Clicker**: 22.6 MPa
- **G-Cem® Capsule**: 11.4 MPa
- **BioCem®**: 13.0 MPa
- **MaxCem™**: 15.8 MPa
- **Multilink® Sprint**: 13.3 MPa
- **PANAVIA® F 2.0**: 15.2 MPa

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**BOND TO VARIETY OF RESTORATION SUBSTRATES**

- **Dagomom**: 12.36 MPa (CC)
- **Wiron 88**: 19.85 MPa (CC)
- **Zirconia**: 25.00 MPa (LC), 20.10 MPa (CC)
- **Ceramic**: 16.81 MPa (LC), 13.45 MPa (CC)
- **Reator**: 14.36 MPa (CC)


**LC = Light-Curing**

**CC = Chemical-Curing**

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VOCO is not the holder of the mentioned trade marks.
Bifi x® SE

RELY ON OUR COMPETENCE

A high flexible strength and low water solubility are key parameters to ensure long lasting success rates with your cemented work. Bifi x SE excels in both categories with significantly better values than other materials.

Low 5–10 micron film thickness

Bifi x SE has a low film thickness of only 5–10 microns. This ensures that the restorations do not “jack up”, saving you adjustment time.
### Cut Down Your Time Consuming Cementing Steps to 4 Easy Steps with Bifix SE

<table>
<thead>
<tr>
<th>STEPS</th>
<th>TYPICAL TOTAL ETCH RESIN CEMENT</th>
<th>Bifix SE</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>Etching</td>
<td>n/a</td>
</tr>
<tr>
<td>2</td>
<td>Rinse</td>
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</tr>
<tr>
<td>3</td>
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</tr>
<tr>
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</tr>
<tr>
<td>8</td>
<td>Spread bond with air</td>
<td>n/a</td>
</tr>
<tr>
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<td>10</td>
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<tr>
<td>11</td>
<td>Seat the restoration</td>
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</tr>
<tr>
<td>12</td>
<td>Remove Excess</td>
<td></td>
</tr>
<tr>
<td>13</td>
<td>Light- or self-cure cement</td>
<td></td>
</tr>
</tbody>
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- **Easy Gel-Phase Excess Removal**
  - Tack light-cure Bifix SE for 1–2 seconds per surface (mesio-oral, disto-oral, mesio-buccal, disto-buccal).
  - The excess gel-like material is easily removed with a scaler.
Bifix® SE

FAST FORWARD WITH CONFIDENCE

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<td>neutral</td>
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</table>

- Kit 3-5 gm QuickMix syringes, shades U, T and WO, mixing tips type 14 and 15, type 1 intra-oral tips 1784
- 1-5 gm QuickMix syringe, shade T (transparent), mixing tips type 14 and 15, type 1 application tips 1786
- 1-5 gm QuickMix syringe, shade WO (white-opaque), mixing tips type 14 and 15, type 1 application tips 1787
- 1-5 gm QuickMix syringe, shade U (universal), mixing tips type 14 and 15, type 1 application tips 1785

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